

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended):

A bond out chip comprising:

a first chip having an active core portion; and

a plurality of input/output pads which are disposed on at least one second chip having a disabled core portion and adjacent to said first chip, said pads being [and which are] communicatively coupled to said first chip.

Claim 2 (original): The bond out chip of claim 1 wherein said first chip and said at least one second chip are spaced apart and are separated by at least one scribe line.

Claim 3 (original): The bond out chip of claim 1 wherein said first chip is substantially identical in architecture to a production chip with the exception of a connection layer.

Claim 4 (original): The bond out chip of claim 3 wherein at least one second chip is substantially identical in architecture to said first chip, with the exception of a connection layer.

Claim 5 (original): The bond out chip of claim 4 wherein said first chip and said at least one second chip are formed on a semiconductor wafer.

Claim 6 (original): The bond out chip of claim 5 wherein said wafer has plurality of reticle zones, and said first chip and said at least one second chip each reside within the same reticle zone.

Claim 7 (canceled)

Claim 8 (currently amended): The bond out chip of claim 7 1 wherein said disabled core portion is disabled by use of a at least one connection layer, said active core portion is activated by use of said at least one connection layer, and said plurality of input/output pads are communicatively coupled to said first chip by use of an interconnection layer which is disposed above said at least one connection layer and which traverses said at least one scribe line.

Claim 9 (original): The bond out chip of claim 1 wherein said at least one second chip further comprises a plurality of input/output buffers which are communicatively coupled to said first chip.

Claim 10 (original): The bond out chip of claim 1 wherein said first chip comprises a microcontroller.

Claim 11 (currently amended):

A bond out chip formed on a semiconductor wafer comprising:

a first chip having an active core portion and which is substantially identical in architecture to a production chip with the exception of at least one connection layer; and

an adjacent chip which is substantially identical in architecture to said first chip with the exception of said at least one connection layer, which is spaced apart from said first chip and separated from said first chip by a scribe line, and which includes a

disabled core portion and a plurality of input/output buffers and pads which are communicatively coupled to said first chip across said scribe line and which are adapted to allow said first chip to ~~be coupled to an in-circuit emulator~~ receive test signals.

Claim 12 (original): The bond out chip of claim 11 wherein said first chip further includes a plurality of drivers for ~~communicating with said in-circuit emulator~~ receiving said test signals, and which are communicatively coupled to said plurality of input/output buffers and pads.

Claim 13 (original): The bond out chip of claim 12 further comprising a connection layer for activating said plurality of drivers and communicatively coupling said input/output buffers and pads to said first chip.

Claim 14 (original): The bond out chip of claim 13 wherein said first chip comprises a microcontroller.